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FGL40N120AN 1200V NPT IGBT

Features

- High speed switching
- Low saturation voltage : V_{CE(sat)} = 2.6 V @ I_C = 40A
- High input impedance

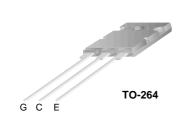
Applications

Induction Heating, UPS, AC & DC motor controls and general purpose inverters.



Description

Employing NPT technology, Fairchild's AN series of IGBTs provides low conduction and switching losses. The AN series offers an solution for application such as induction heating (IH), motor control, general purpose inverters and uninterruptible power supplies (UPS).





Absolute Maximum Ratings

Symbol	Parameter		FGL40N120AN	Units	
V _{CES}	Collector-Emitter Voltage		1200	V	
V _{GES}	Gate-Emitter Voltage		±25	V	
I _C	Collector Current	@T _C = 25°C	64	A	
	Collector Current	@T _C = 100°C	40	A	
I _{CM(1)}	Pulsed Collector Current		160	A	
P _D	Maximum Power Dissipation	@T _C = 25°C	500	W	
	Maximum Power Dissipation	@T _C = 100°C	200	W	
SCWT	Short Circuit Withstand Time, $V_{CE} = 600V, V_{GE} = 15V, T_{C} = 125^{\circ}C$		10	μs	
TJ	Operating Junction Temperature		-55 to +150	°C	
T _{STG}	Storage Temperature Range		-55 to +150	°C	
Τ _L	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 seconds		300	°C	

Notes:

(1) Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$ (IGBT)	Thermal Resistance, Junction-to-Case		0.25	°C/W
R _{0JA} Thermal Resistance, Junction-to-Ambient			25	°C/W

		Device Pacl		je Reel Size	Тар	Tape Width		Quantity 25	
		TO-264	-						
Electrica	al Char	acteristics of th	e IGB1	T _C = 25°C unless otherwise r	oted				
Symbol		Parameter		Conditions	Min.	Тур.	Max.	Units	
Off Charact	eristics								
BV _{CES}	Collector	-Emitter Breakdown Volta	ge V _{GI}	₌ = 0V, I _C = 1mA	1200			V	
BV _{CES} / ΔT _J	Temperature Coefficient of Breakdown Voltage		own	₌ = 0V, I _C = 1mA		0.6		V/°C	
I _{CES}	Collector	Cut-Off Current	V _{CE}	$_{\rm E}$ = V _{CES} , V _{GE} = 0V			1	mA	
I _{GES}	G-E Leal	kage Current	V _{GI}	$_{\rm E}$ = V _{GES} , V _{CE} = 0V			±250	nA	
On Charact	eristice		·						
V _{GE(th)}		eshold Voltage	I _C =	= 250µA, V _{CE} = V _{GE}	3.5	5.5	7.5	V	
(/)		-	-	= 40A, V _{GE} = 15V		2.6	3.2	V	
V _{CE(sat)}	Collector to Emitter Saturation Voltage			= 40A, V _{GE} = 15V, = 125°C		2.9		V	
			I _C =	= 64A, V _{GE} = 15V		3.15		V	
Dynamic Cl						2200			
C _{ies}	Input Ca		VCE	_E = 30V, V _{GE} = 0V		3200		pF	
C _{oes}	Output Capacitance Reverse Transfer Capacitance			1MHz		370 125		pF pF	
C _{res}	Reverse	Transier Capacitance				125		μ	
Switching C	1					45			
t _{d(on)}		Delay Time				15		ns	
t _r	Rise Tim	e Delay Time				20 110		ns	
t _{d(off)}	Fall Time			_C = 600V, I _C = 40A, = 5Ω, V _{GE} = 15V,		40	80	ns ns	
t _f E _{on}		Switching Loss		uctive Load, $T_C = 25^{\circ}C$		2.3	3.45	mJ	
E _{off}		Switching Loss				1.1	1.65	mJ	
E _{ts}		tching Loss				3.4	5.1	mJ	
t _{d(on)}	Turn-On	Delay Time				20		ns	
t _r	Rise Tim	-				25		ns	
t _{d(off)}	Turn-Off	Delay Time	Ver	_c = 600V, I _C = 40A,		120		ns	
t _f	Fall Time	•	R _G	$R_{G} = 5\Omega, V_{GE} = 15V,$		45		ns	
Eon	Turn-On	Switching Loss	Ind	uctive Load, T _C = 125°C		2.5		mJ	
E _{off}	Turn-Off	Switching Loss				1.8		mJ	
E _{ts}	Total Swi	tching Loss				4.3		mJ	
Qg	Total Gat	e charge		600)/ 1 404		220	330	nC	
Q _{ge}	Gate-Em	itter Charge		₌ = 600V, I _C = 40A, ₌ = 15V		25	38	nC	
Q _{gc}	Gate-Col	lector Charge		-		130	195	nC	

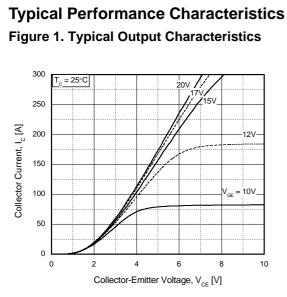


Figure 3. Saturation Voltage vs. Case Temperature at Variant Current Level

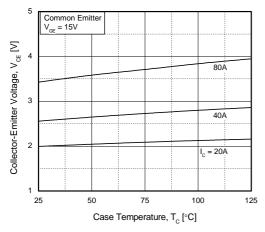


Figure 5. Saturation Voltage vs. V_{GE}

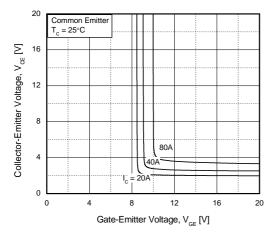


Figure 2. Typical Saturation Voltage Characteristics

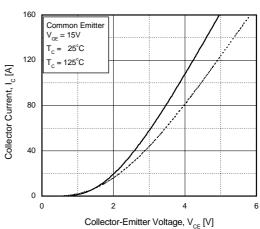


Figure 4. Load Current vs. Frequency

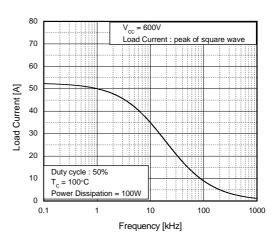
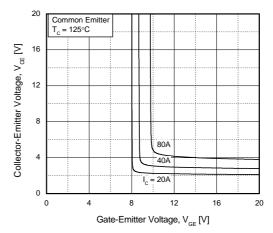


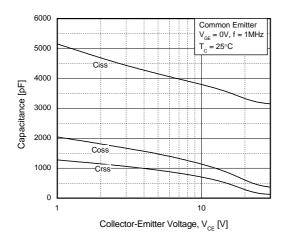
Figure 6. Saturation Voltage vs. V_{GE}



FGL40N120AN 1200V NPT IGBT

Typical Performance Characteristics (Continued)







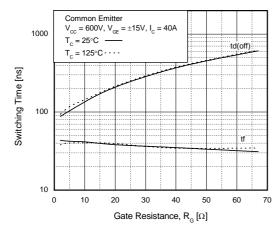


Figure 11. Turn-On Characteristics vs. Collector Current

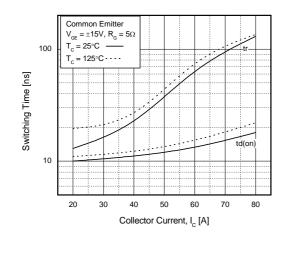


Figure 8. Turn-On Characteristics vs. Gate Resistance

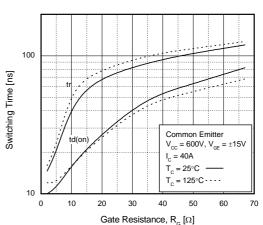


Figure 10. Switching Loss vs. Gate Resistance

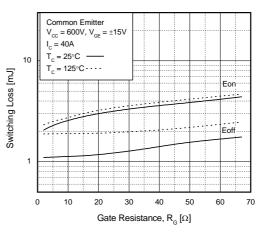
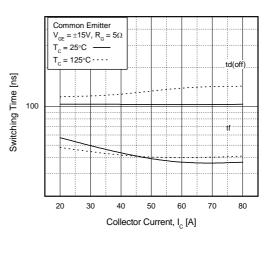
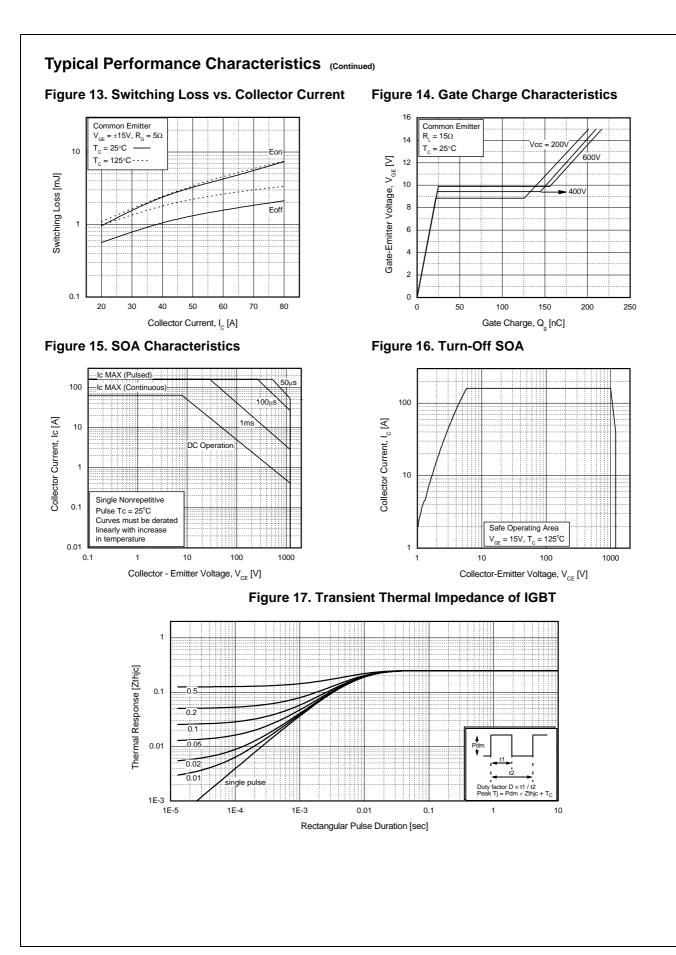
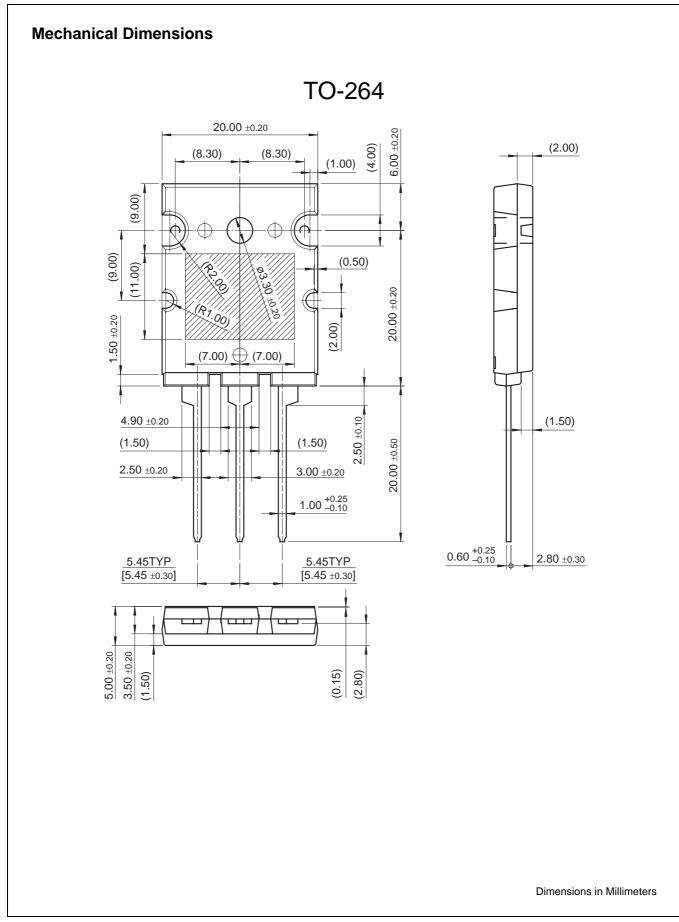


Figure 12. Turn-Off Characteristics vs. Collector Current









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